Price of Optical Module Wire Bonding Machine



Overview

K950 Automatic Optical Module Wire Bonder ApplicationsThe K950 Automatic Optical Module Wire Bonder is a high-speed, high-precision semiconductor wire bond.

Key Takeaways

Optical module wire bonding machines typically range from $10,000 to over $80,000 depending on bonding type, precision, and automation level. Price Ranges by Bonding TypeBall Bonding (Gold Wire): These machines are used for high-precision connections in microelectronics and optical modules. Prices generally range from $25,000 to $80,000+, reflecting the need for precise control systems and high-purity materials.

Wedge Bonding (Aluminum Wire): Common in LEDs, automotive electronics, and power semiconductors, these machines are more cost-effective, typically priced between $10,000 and $40,000.

Factors Affecting Cost

Automation Level: Fully automated machines with AI-driven precision and multi-wire bonding capabilities command higher prices due to improved throughput and reduced labor costs. Precision and Miniaturization: Machines capable of handling smaller chip designs or optical modules with ultra-fine wires are more expensive. Materials and Consumables: Gold wire machines are costlier than aluminum or copper due to material costs.

© 2026 KENHARDT OPTICAL NETWORKS - All rights reserved

Long-term expenses include capillaries, wires, and maintenance. Advanced Features: Photonic wire bonding machines, which use 3D nano-printing for optical integration, are specialized and may exceed standard wire bonding machine prices due to their precision and ability to handle complex optical elements.

Additional Considerations

Refurbished or Pre-Owned Machines: Certified pre-owned machines can offer significant savings while maintaining performance. Compliance and Standards: Ensure machines meet industry standards such as IPC-J-STD-030 and ISO 9001 for quality assurance.

Long-

Term RO

I: Consider operational efficiency, energy consumption, and compatibility with production volume when evaluating cost. In summary, the price of optical module wire bonding machines varies widely based on bonding type, precision, and automation. For standard semiconductor applications, expect $10,000–$80,000+, while advanced photonic wire bonding solutions may be higher due to specialized 3D nano-printing capabilities.

Article Content

K950 Automatic Optical Module Wire Bonder Applications

The K950 Automatic Optical Module Wire Bonder is a high-speed, high-precision semiconductor wire bonding machine designed specifically for COB (Chip-on-Board) optical module packaging.

wire bonding machine Price

Comparing wire bonding machine prices. You can easily wholesale quality wire bonding machine at wholesale prices on Made-in-China .

Vanguard Automation | Photonic Wire Bonds

Vanguard Automation offers machines and processes for 3D nano-printing in the field of photonic integration and packaging. Our solutions cover the full range from small-scale prototyping to fully

Wire bonding machine price-AliExpress

Discover the average wire bonding machine price for small to medium manufacturers, factors affecting costs, and how to evaluate value on platforms like AliExpress in this detailed 2025 guide.

© 2026 KENHARDT OPTICAL NETWORKS - All rights reserved

New & Used Wire Bonders for sale. Kulicke & Soffa | Machinio

Kulicke & Soffa, West Bond, ITW, ASM, Palomar, MEI, Hesse Mechatronics, and ESEC wire bonders for sale. Find used wire bonding equipment on Machinio.

Full text of "NEW"

Full text of "NEW" See other formats Word . the, > < br to of and a : " in you that i it he is was for - with) on (? his as this ; be at but not have had from will are they -- ! all by if him one your

WebProcure

WebProcure offers best-in-class functionality, reaching end-to-end from requester to procurement buyer to merchant, and all the way back! Designed specifically for the public sector.

Wire Bonding Machines: Technology, Types & Buying Guide

Complete guide to wire bonding machines covering technology, types, wire materials, pricing, and applications. Expert sourcing & integration by Himalaya Semiconductor.

Wire Bonding Machine

Discover wire bonding machines with CE certification, ultrasonic welding tech, and PLC control for precise, efficient aluminum & copper wire bonding in battery, LED, and IGBT applications.

Ansys | Engineering Simulation Software

Ansys engineering simulation and 3D design software delivers product modeling solutions with unmatched scalability and a comprehensive multiphysics foundation.

How to Choose the Best Wire Bonding Machine: A Complete Buying

Discover what to look for in a wire bonding machine, including types, key features, price ranges, and expert tips to make an informed purchase decision.

"Optical Bonding Machine Price"

The Optical Bonding Machine Price is a key item within our extensive Laser Welding Machine selection 2026, laser welding machine prices are expected to decrease due to technological

Wire Bonder Machines

Discover automatic wire bonder machines with CE certification, ideal for battery packs and LED assembly. Explore high-speed ultrasonic wire bonding solutions.

Wire Bonding Machine Price

© 2026 KENHARDT OPTICAL NETWORKS - All rights reserved

Discover wire bonding machines at factory prices, featuring CE certification and precision pulse heating for metal, FFC, FPC applications.

Wholesale Wire Bonding Machine Products at Factory Prices from ...

Find wholesale wire bonding machine manufacturers from China, India, Korea, and so on. Source good quality wire bonding machine products for sale at factory prices from online Chinese, Indian, Korean,

Coherent Market Insights: Market Research and B2B Consulting

Coherent Market Insights provides Market Research, Customized Research, Business Intelligence, B2B Consulting, and Advisory Services to clients worldwide.

Wirebond AOI Machine

Application Post Die Bond/Wirebond Inspection: The primary application of the Wirebond AOI Machine is in post die bond/wirebond inspection, ensuring the integrity and quality of wirebond connections

Semiconductor Bonding Equipment Market Size, Share, Analysis

Semiconductor Bonding Equipment Market Analysis by Mordor Intelligence The semiconductor bonding equipment market size in 2026 is estimated at USD 596.47 million, growing

Contact Us

Continue your research online:

Website: https://kenhardtprimary.co.za
Technical inquiry: https://kenhardtprimary.co.za/project-desk.html
African project coordination: Century City, Cape Town, Western Cape, South Africa

This document is for preliminary research. Verify specifications against current standards, product documentation and project requirements.

© 2026 KENHARDT OPTICAL NETWORKS - All rights reserved